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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I <sup>2</sup> C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 10x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LFQFP (7x7)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f100gfab-30">https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f100gfab-30</a>

**Table 1-1. List of Ordering Part Numbers**

(5/12)

Pin count	Package	Data flash	Fields of Application <small>Note</small>	Ordering Part Number
48 pins	48-pin plastic LFQFP (7 × 7 mm, 0.5 mm pitch)	Mounted	A	R5F100GAAFB#V0, R5F100GCAFB#V0, R5F100GDADF#V0, R5F100GEAFB#V0, R5F100GFADF#V0, R5F100GGAFB#V0, R5F100GHAFB#V0, R5F100GJAFB#V0, R5F100GKAFB#V0, R5F100GLAFB#V0 R5F100GAAFB#X0, R5F100GCAFB#X0, R5F100GDADF#X0, R5F100GEAFB#X0, R5F100GFADF#X0, R5F100GGAFB#X0, R5F100GHAFB#X0, R5F100GJAFB#X0, R5F100GKAFB#X0, R5F100GLAFB#X0
			D	R5F100GADFB#V0, R5F100GCDFB#V0, R5F100GDDFB#V0, R5F100GEDFB#V0, R5F100GFDFB#V0, R5F100GGDFB#V0, R5F100GHDFB#V0, R5F100GJDFB#V0, R5F100GKDFB#V0, R5F100GLDFB#V0 R5F100GADFB#X0, R5F100GCDFB#X0, R5F100GDDFB#X0, R5F100GEDFB#X0, R5F100GFDFB#X0, R5F100GGDFB#X0, R5F100GHDFB#X0, R5F100GJDFB#X0, R5F100GKDFB#X0, R5F100GLDFB#X0
			G	R5F100GAGFB#V0, R5F100GCGFB#V0, R5F100GDGFB#V0, R5F100GEGFB#V0, R5F100GFGFB#V0, R5F100GGGFB#V0, R5F100GHGFB#V0, R5F100GJGFB#V0 R5F100GAGFB#X0, R5F100GCGFB#X0, R5F100GDGFB#X0, R5F100GEGFB#X0, R5F100GFGFB#X0, R5F100GGGFB#X0, R5F100GHGFB#X0, R5F100GJGFB#X0
		Not mounted	A	R5F101GAAFB#V0, R5F101GCAFB#V0, R5F101GDADF#V0, R5F101GEAFB#V0, R5F101GFADF#V0, R5F101GGAFB#V0, R5F101GHAFB#V0, R5F101GJAFB#V0, R5F101GKAFB#V0, R5F101GLAFB#V0 R5F101GAAFB#X0, R5F101GCAFB#X0, R5F101GDADF#X0, R5F101GEAFB#X0, R5F101GFADF#X0, R5F101GGAFB#X0, R5F101GHAFB#X0, R5F101GJAFB#X0, R5F101GKAFB#X0, R5F101GLAFB#X0
			D	R5F101GADFB#V0, R5F101GCDFB#V0, R5F101GDDFB#V0, R5F101GEDFB#V0, R5F101GFDFB#V0, R5F101GGDFB#V0, R5F101GHDFB#V0, R5F101GJDFB#V0, R5F101GKDFB#V0, R5F101GLDFB#V0 R5F101GADFB#X0, R5F101GCDFB#X0, R5F101GDDFB#X0, R5F101GEDFB#X0, R5F101GFDFB#X0, R5F101GGDFB#X0, R5F101GHDFB#X0, R5F101GJDFB#X0, R5F101GKDFB#X0, R5F101GLDFB#X0

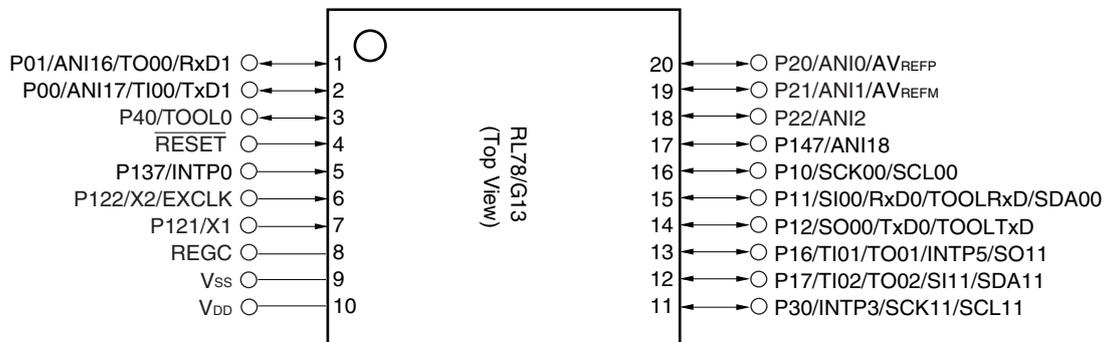
**Note** For the fields of application, refer to **Figure 1-1 Part Number, Memory Size, and Package of RL78/G13.**

**Caution** The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

### 1.3 Pin Configuration (Top View)

#### 1.3.1 20-pin products

- 20-pin plastic LSSOP (7.62 mm (300), 0.65 mm pitch)

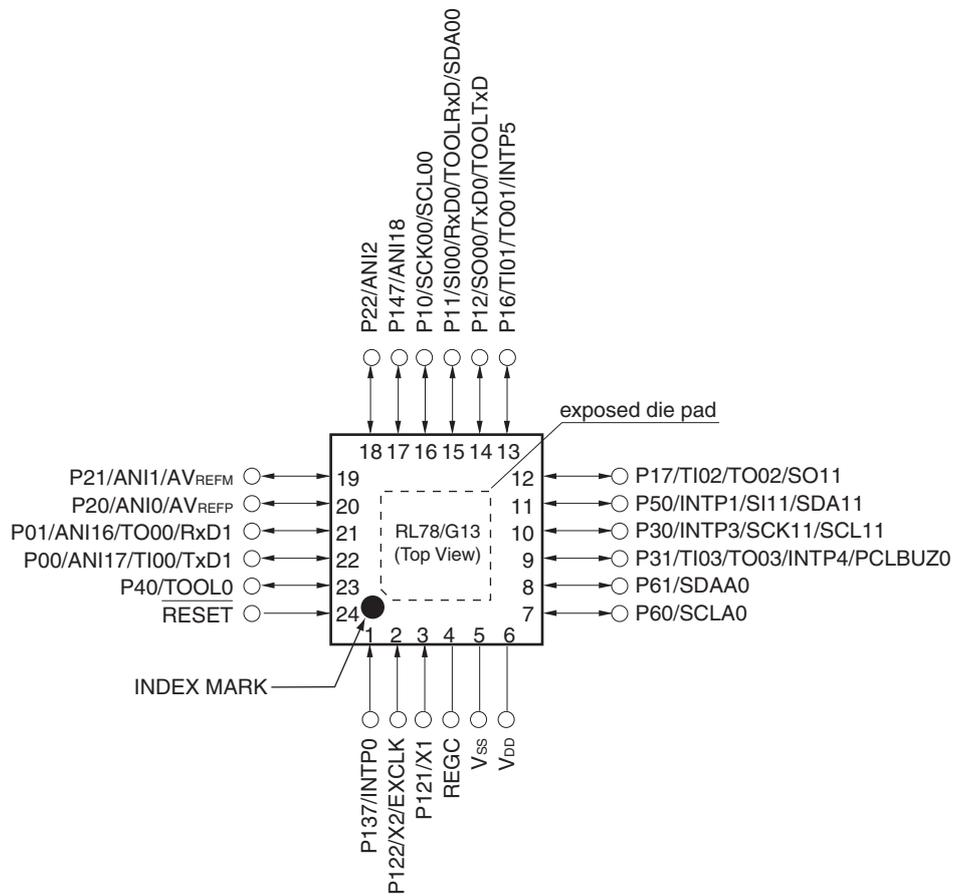


**Caution** Connect the REGC pin to V<sub>SS</sub> via a capacitor (0.47 to 1  $\mu$ F).

**Remark** For pin identification, see 1.4 Pin Identification.

1.3.2 24-pin products

- 24-pin plastic HWQFN (4 × 4 mm, 0.5 mm pitch)

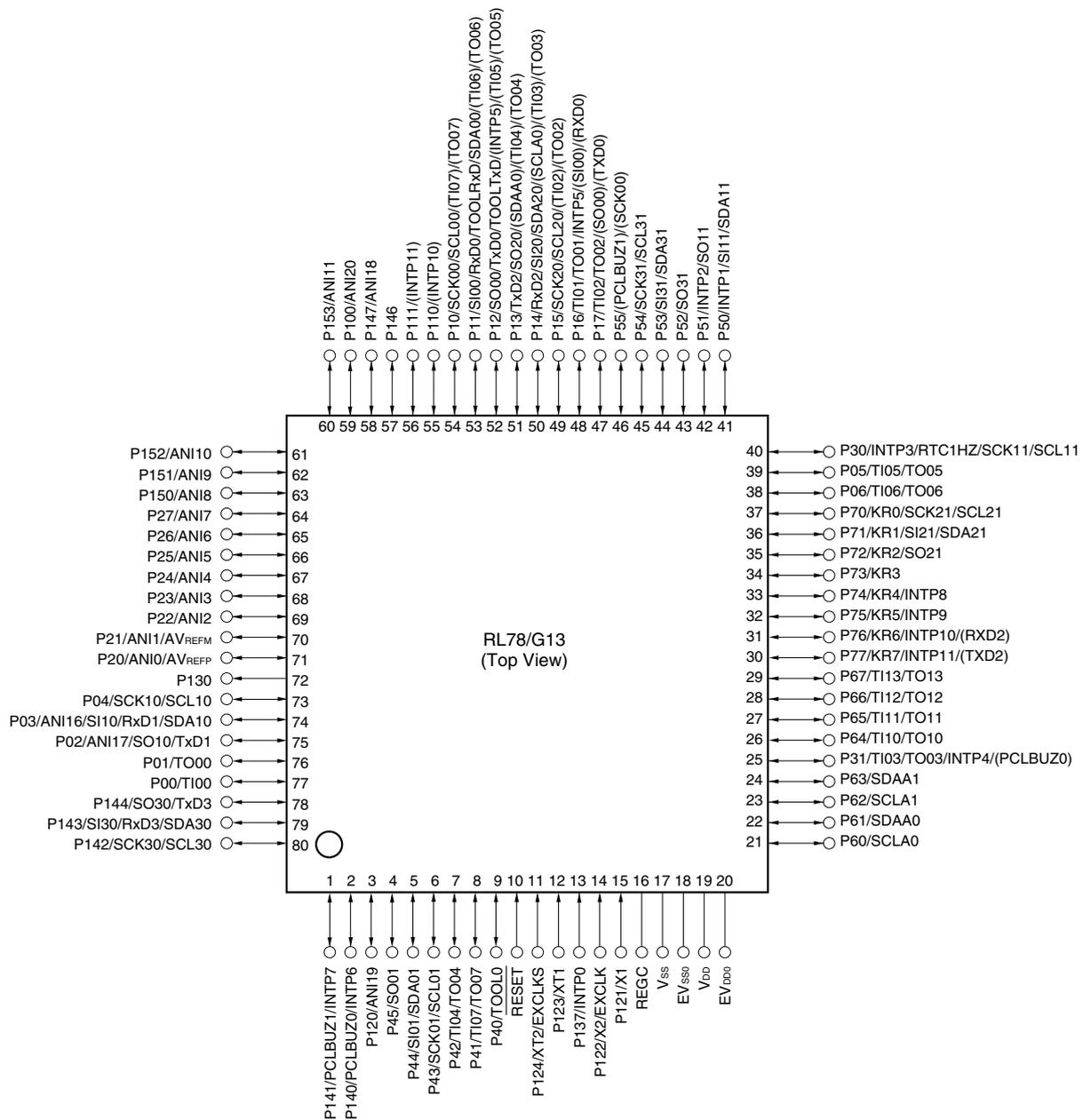


**Caution** Connect the REGC pin to V<sub>SS</sub> via a capacitor (0.47 to 1 μF).

- Remarks**
1. For pin identification, see 1.4 Pin Identification.
  2. It is recommended to connect an exposed die pad to V<sub>SS</sub>.

1.3.12 80-pin products

- 80-pin plastic LQFP (14 × 14 mm, 0.65 mm pitch)
- 80-pin plastic LFQFP (12 × 12 mm, 0.5 mm pitch)

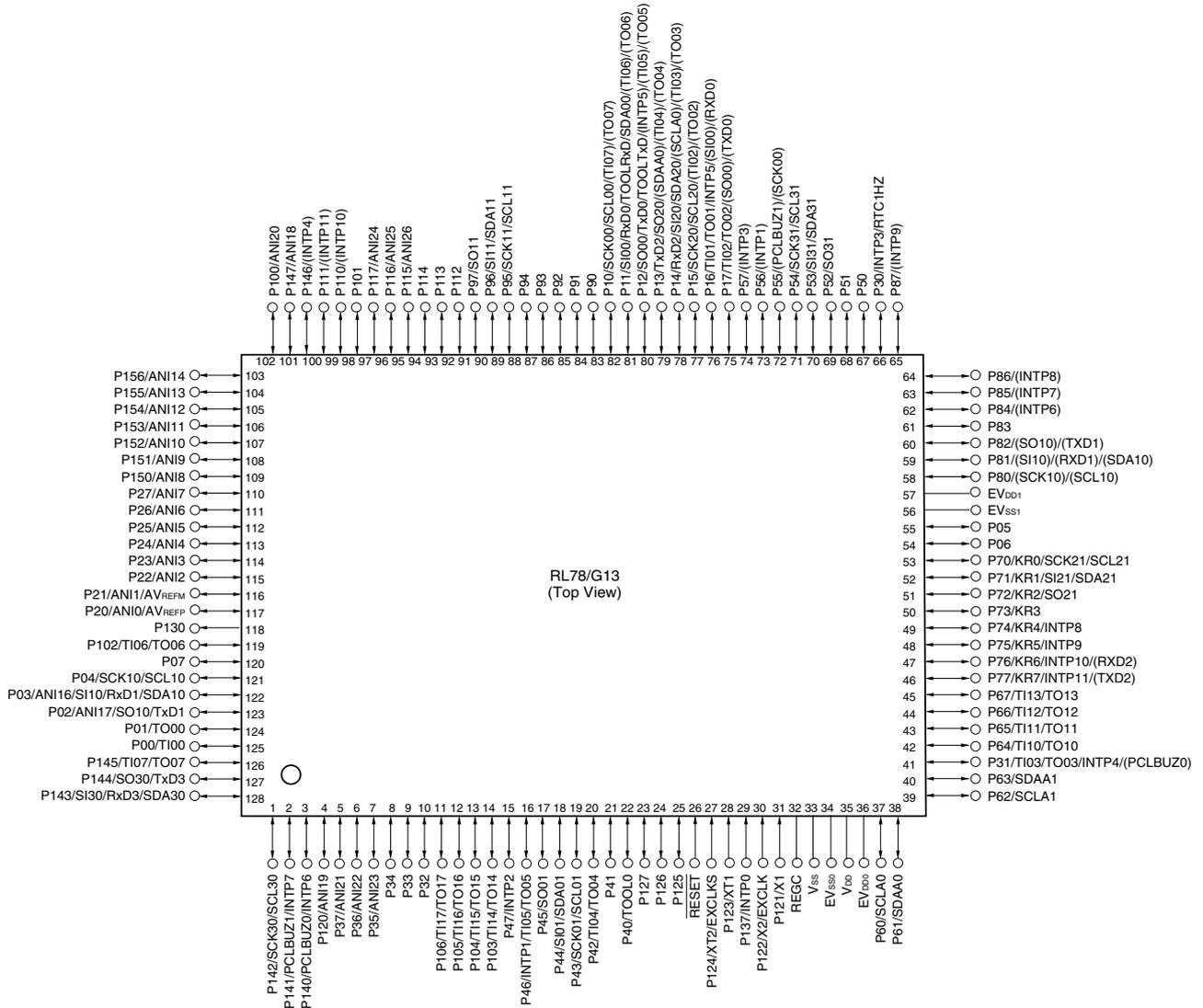


- Cautions**
1. Make EV<sub>SS0</sub> pin the same potential as V<sub>SS</sub> pin.
  2. Make V<sub>DD</sub> pin the potential that is higher than EV<sub>DD0</sub> pin.
  3. Connect the REGC pin to V<sub>SS</sub> via a capacitor (0.47 to 1 μF).

- Remarks**
1. For pin identification, see 1.4 Pin Identification.
  2. When using the microcontroller for an application where the noise generated inside the microcontroller must be reduced, it is recommended to supply separate powers to the V<sub>DD</sub> and EV<sub>DD0</sub> pins and connect the V<sub>SS</sub> and EV<sub>SS0</sub> pins to separate ground lines.
  3. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

1.3.14 128-pin products

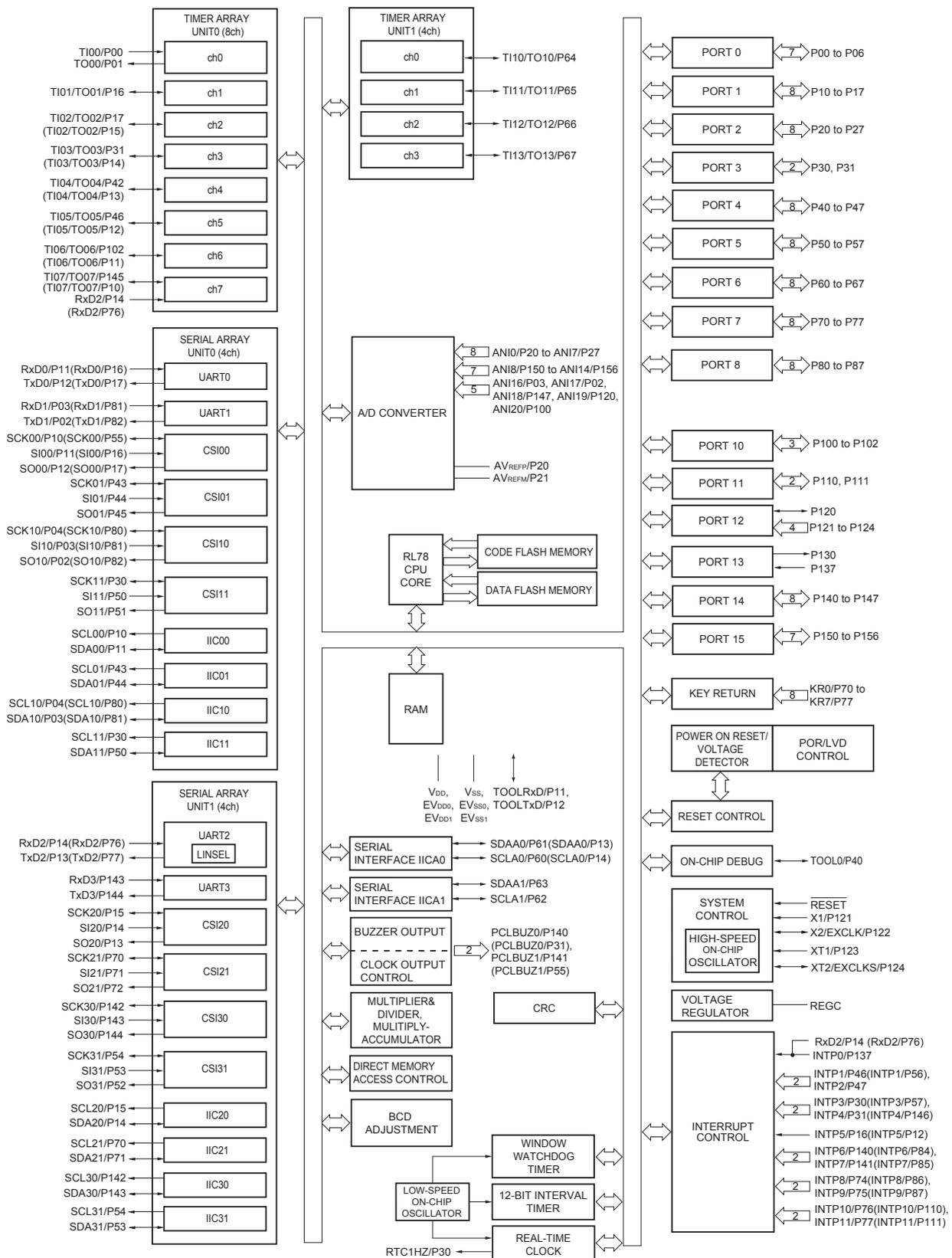
- 128-pin plastic LQFP (14 × 20 mm, 0.5 mm pitch)



- Cautions**
1. Make EVSS0, EVSS1 pins the same potential as Vss pin.
  2. Make VDD pin the potential that is higher than EVDD0, EVDD1 pins (EVDD0 = EVDD1).
  3. Connect the REGC pin to Vss via a capacitor (0.47 to 1 μF).

- Remarks**
1. For pin identification, see 1.4 Pin Identification.
  2. When using the microcontroller for an application where the noise generated inside the microcontroller must be reduced, it is recommended to supply separate powers to the VDD, EVDD0 and EVDD1 pins and connect the Vss, EVSS0 and EVSS1 pins to separate ground lines.
  3. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

1.5.13 100-pin products



**Remark** Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

3. The number of PWM outputs varies depending on the setting of channels in use (the number of masters and slaves) (see **6.9.3 Operation as multiple PWM output function** in the RL78/G13 User's Manual).
4. When setting to PIOR = 1

(2/2)

Item	20-pin		24-pin		25-pin		30-pin		32-pin		36-pin		
	R5F1006x	R5F1016x	R5F1007x	R5F1017x	R5F1008x	R5F1018x	R5F100Ax	R5F101Ax	R5F100Bx	R5F101Bx	R5F100Cx	R5F101Cx	
Clock output/buzzer output	-		1		1		2		2		2		
	<ul style="list-style-type: none"> <li>• 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz</li> <li>(Main system clock: f<sub>MAIN</sub> = 20 MHz operation)</li> </ul>												
8/10-bit resolution A/D converter	6 channels		6 channels		6 channels		8 channels		8 channels		8 channels		
Serial interface	[20-pin, 24-pin, 25-pin products] <ul style="list-style-type: none"> <li>• CSI: 1 channel/simplified I<sup>2</sup>C: 1 channel/UART: 1 channel</li> <li>• CSI: 1 channel/simplified I<sup>2</sup>C: 1 channel/UART: 1 channel</li> </ul> [30-pin, 32-pin products] <ul style="list-style-type: none"> <li>• CSI: 1 channel/simplified I<sup>2</sup>C: 1 channel/UART: 1 channel</li> <li>• CSI: 1 channel/simplified I<sup>2</sup>C: 1 channel/UART: 1 channel</li> <li>• CSI: 1 channel/simplified I<sup>2</sup>C: 1 channel/UART (UART supporting LIN-bus): 1 channel</li> </ul> [36-pin products] <ul style="list-style-type: none"> <li>• CSI: 1 channel/simplified I<sup>2</sup>C: 1 channel/UART: 1 channel</li> <li>• CSI: 1 channel/simplified I<sup>2</sup>C: 1 channel/UART: 1 channel</li> <li>• CSI: 2 channels/simplified I<sup>2</sup>C: 2 channels/UART (UART supporting LIN-bus): 1 channel</li> </ul>												
	I <sup>2</sup> C bus	-		1 channel									
Multiplier and divider/multiply-accumulator	<ul style="list-style-type: none"> <li>• 16 bits × 16 bits = 32 bits (Unsigned or signed)</li> <li>• 32 bits ÷ 32 bits = 32 bits (Unsigned)</li> <li>• 16 bits × 16 bits + 32 bits = 32 bits (Unsigned or signed)</li> </ul>												
DMA controller	2 channels												
Vectored interrupt sources	Internal	23		24		24		27		27		27	
	External	3		5		5		6		6		6	
Key interrupt	-												
Reset	<ul style="list-style-type: none"> <li>• Reset by RESET pin</li> <li>• Internal reset by watchdog timer</li> <li>• Internal reset by power-on-reset</li> <li>• Internal reset by voltage detector</li> <li>• Internal reset by illegal instruction execution <sup>Note</sup></li> <li>• Internal reset by RAM parity error</li> <li>• Internal reset by illegal-memory access</li> </ul>												
Power-on-reset circuit	<ul style="list-style-type: none"> <li>• Power-on-reset: 1.51 V (TYP.)</li> <li>• Power-down-reset: 1.50 V (TYP.)</li> </ul>												
Voltage detector	<ul style="list-style-type: none"> <li>• Rising edge : 1.67 V to 4.06 V (14 stages)</li> <li>• Falling edge : 1.63 V to 3.98 V (14 stages)</li> </ul>												
On-chip debug function	Provided												
Power supply voltage	V <sub>DD</sub> = 1.6 to 5.5 V (T <sub>A</sub> = -40 to +85°C) V <sub>DD</sub> = 2.4 to 5.5 V (T <sub>A</sub> = -40 to +105°C)												
Operating ambient temperature	T <sub>A</sub> = 40 to +85°C (A: Consumer applications, D: Industrial applications ) T <sub>A</sub> = 40 to +105°C (G: Industrial applications)												

**Note** The illegal instruction is generated when instruction code FFH is executed.

Reset by the illegal instruction execution not issued by emulation with the in-circuit emulator or on-chip debug emulator.

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## 2. ELECTRICAL SPECIFICATIONS ( $T_A = -40$ to $+85^\circ\text{C}$ )

This chapter describes the following electrical specifications.

Target products A: Consumer applications  $T_A = -40$  to  $+85^\circ\text{C}$

R5F100xxAxx, R5F101xxAxx

D: Industrial applications  $T_A = -40$  to  $+85^\circ\text{C}$

R5F100xxDxx, R5F101xxDxx

G: Industrial applications when  $T_A = -40$  to  $+105^\circ\text{C}$  products is used in the range of  $T_A = -40$  to  $+85^\circ\text{C}$

R5F100xxGxx

- Cautions**
- 1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.**
  - 2. With products not provided with an  $EV_{DD0}$ ,  $EV_{DD1}$ ,  $EV_{SS0}$ , or  $EV_{SS1}$  pin, replace  $EV_{DD0}$  and  $EV_{DD1}$  with  $V_{DD}$ , or replace  $EV_{SS0}$  and  $EV_{SS1}$  with  $V_{SS}$ .**
  - 3. The pins mounted depend on the product. Refer to 2.1 Port Function to 2.2.1 Functions for each product.**

(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ E<sub>VDD0</sub> = E<sub>VDD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = E<sub>VSS0</sub> = E<sub>VSS1</sub> = 0 V) (5/5)

Items	Symbol	Conditions	MIN.	TYP.	MAX.	Unit		
Input leakage current, high	I <sub>LIH1</sub>	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	V <sub>I</sub> = E <sub>VDD0</sub>		1	μA		
	I <sub>LIH2</sub>	P20 to P27, P137, P150 to P156, RESET	V <sub>I</sub> = V <sub>DD</sub>		1	μA		
	I <sub>LIH3</sub>	P121 to P124 (X1, X2, XT1, XT2, EXCLK, EXCLKS)	V <sub>I</sub> = V <sub>DD</sub>		In input port or external clock input	1	μA	
			In resonator connection	10	μA			
Input leakage current, low	I <sub>LIL1</sub>	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	V <sub>I</sub> = E <sub>VSS0</sub>		-1	μA		
	I <sub>LIL2</sub>	P20 to P27, P137, P150 to P156, RESET	V <sub>I</sub> = V <sub>SS</sub>		-1	μA		
	I <sub>LIL3</sub>	P121 to P124 (X1, X2, XT1, XT2, EXCLK, EXCLKS)	V <sub>I</sub> = V <sub>SS</sub>		In input port or external clock input	-1	μA	
			In resonator connection	-10	μA			
On-chip pll-up resistance	R <sub>U</sub>	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	V <sub>I</sub> = E <sub>VSS0</sub> , In input port		10	20	100	kΩ

**Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

- Notes**
1. Total current flowing into V<sub>DD</sub> and EV<sub>DD0</sub>, including the input leakage current flowing when the level of the input pin is fixed to V<sub>DD</sub>, EV<sub>DD0</sub> or V<sub>SS</sub>, EV<sub>SS0</sub>. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
  2. When high-speed on-chip oscillator and subsystem clock are stopped.
  3. When high-speed system clock and subsystem clock are stopped.
  4. When high-speed on-chip oscillator and high-speed system clock are stopped. When AMPHS1 = 1 (Ultra-low power consumption oscillation). However, not including the current flowing into the RTC, 12-bit interval timer, and watchdog timer.
  5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.
    - HS (high-speed main) mode: 2.7 V ≤ V<sub>DD</sub> ≤ 5.5 V @ 1 MHz to 32 MHz
    - 2.4 V ≤ V<sub>DD</sub> ≤ 5.5 V @ 1 MHz to 16 MHz
    - LS (low-speed main) mode: 1.8 V ≤ V<sub>DD</sub> ≤ 5.5 V @ 1 MHz to 8 MHz
    - LV (low-voltage main) mode: 1.6 V ≤ V<sub>DD</sub> ≤ 5.5 V @ 1 MHz to 4 MHz

- Remarks**
1. f<sub>MX</sub>: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
  2. f<sub>IH</sub>: High-speed on-chip oscillator clock frequency
  3. f<sub>SUB</sub>: Subsystem clock frequency (XT1 clock oscillation frequency)
  4. Except subsystem clock operation, temperature condition of the TYP. value is T<sub>A</sub> = 25°C

## (3) During communication at same potential (CSI mode) (master mode, SCKp... internal clock output)

(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time	t <sub>KCY1</sub>	t <sub>KCY1</sub> ≥ 4/f <sub>CLK</sub>	2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	125		500		1000	ns
			2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	250		500		1000	ns
			1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	500		500		1000	ns
			1.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	1000		1000		1000	ns
			1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	—		1000		1000	ns
SCKp high-/low-level width	t <sub>KH1</sub> , t <sub>KL1</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	t <sub>KCY1</sub> /2 – 12		t <sub>KCY1</sub> /2 – 50		t <sub>KCY1</sub> /2 – 50	ns	
		2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	t <sub>KCY1</sub> /2 – 18		t <sub>KCY1</sub> /2 – 50		t <sub>KCY1</sub> /2 – 50	ns	
		2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	t <sub>KCY1</sub> /2 – 38		t <sub>KCY1</sub> /2 – 50		t <sub>KCY1</sub> /2 – 50	ns	
		1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	t <sub>KCY1</sub> /2 – 50		t <sub>KCY1</sub> /2 – 50		t <sub>KCY1</sub> /2 – 50	ns	
		1.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	t <sub>KCY1</sub> /2 – 100		t <sub>KCY1</sub> /2 – 100		t <sub>KCY1</sub> /2 – 100	ns	
		1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	—		t <sub>KCY1</sub> /2 – 100		t <sub>KCY1</sub> /2 – 100	ns	
Slp setup time (to SCKp↑) <small>Note 1</small>	t <sub>SIK1</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	44		110		110	ns	
		2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	44		110		110	ns	
		2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	75		110		110	ns	
		1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	110		110		110	ns	
		1.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	220		220		220	ns	
		1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	—		220		220	ns	
Slp hold time (from SCKp↑) <small>Note 2</small>	t <sub>KH1</sub>	1.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	19		19		19	ns	
		1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V	—		19		19	ns	
Delay time from SCKp↓ to SOp output <small>Note 3</small>	t <sub>KSO1</sub>	1.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V C = 30 pF <sup>Note 4</sup>		25		25		25	ns
		1.6 V ≤ EV <sub>DD0</sub> ≤ 5.5 V C = 30 pF <sup>Note 4</sup>		—		25		25	ns

- Notes**
1. When DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 0, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 1. The Slp setup time becomes “to SCKp↓” when DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 1, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 0.
  2. When DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 0, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 1. The Slp hold time becomes “from SCKp↓” when DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 1, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 0.
  3. When DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 0, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 1. The delay time to SOp output becomes “from SCKp↑” when DAP<sub>mn</sub> = 0 and CKP<sub>mn</sub> = 1, or DAP<sub>mn</sub> = 1 and CKP<sub>mn</sub> = 0.
  4. C is the load capacitance of the SCKp and SOp output lines.

**Caution** Select the normal input buffer for the Slp pin and the normal output mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

(5) During communication at same potential (simplified I<sup>2</sup>C mode) (1/2)(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCLr clock frequency	f <sub>SCL</sub>	2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, C <sub>b</sub> = 50 pF, R <sub>b</sub> = 2.7 kΩ		1000 Note 1		400 Note 1		400 Note 1	kHz
		1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 3 kΩ		400 Note 1		400 Note 1		400 Note 1	kHz
		1.8 V ≤ EV <sub>DD0</sub> < 2.7 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 5 kΩ		300 Note 1		300 Note 1		300 Note 1	kHz
		1.7 V ≤ EV <sub>DD0</sub> < 1.8 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 5 kΩ		250 Note 1		250 Note 1		250 Note 1	kHz
		1.6 V ≤ EV <sub>DD0</sub> < 1.8 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 5 kΩ		—		250 Note 1		250 Note 1	kHz
Hold time when SCLr = "L"	t <sub>LOW</sub>	2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, C <sub>b</sub> = 50 pF, R <sub>b</sub> = 2.7 kΩ	475		1150		1150		ns
		1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 3 kΩ	1150		1150		1150		ns
		1.8 V ≤ EV <sub>DD0</sub> < 2.7 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 5 kΩ	1550		1550		1550		ns
		1.7 V ≤ EV <sub>DD0</sub> < 1.8 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 5 kΩ	1850		1850		1850		ns
		1.6 V ≤ EV <sub>DD0</sub> < 1.8 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 5 kΩ	—		1850		1850		ns
Hold time when SCLr = "H"	t <sub>HIGH</sub>	2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, C <sub>b</sub> = 50 pF, R <sub>b</sub> = 2.7 kΩ	475		1150		1150		ns
		1.8 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 3 kΩ	1150		1150		1150		ns
		1.8 V ≤ EV <sub>DD0</sub> < 2.7 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 5 kΩ	1550		1550		1550		ns
		1.7 V ≤ EV <sub>DD0</sub> < 1.8 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 5 kΩ	1850		1850		1850		ns
		1.6 V ≤ EV <sub>DD0</sub> < 1.8 V, C <sub>b</sub> = 100 pF, R <sub>b</sub> = 5 kΩ	—		1850		1850		ns

(Notes and Caution are listed on the next page, and Remarks are listed on the page after the next page.)

(3) When reference voltage (+) = V<sub>DD</sub> (ADREFP1 = 0, ADREFP0 = 0), reference voltage (-) = V<sub>SS</sub> (ADREFM = 0), target pin : ANI0 to ANI14, ANI16 to ANI26, internal reference voltage, and temperature sensor output voltage

(T<sub>A</sub> = -40 to +85°C, 1.6 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V, Reference voltage (+) = V<sub>DD</sub>, Reference voltage (-) = V<sub>SS</sub>)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error <sup>Note 1</sup>	AINL	10-bit resolution	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V		1.2	±7.0	LSB
			1.6 V ≤ V <sub>DD</sub> ≤ 5.5 V <small>Note 3</small>		1.2	±10.5	LSB
Conversion time	t <sub>CONV</sub>	10-bit resolution Target pin: ANI0 to ANI14, ANI16 to ANI26	3.6 V ≤ V <sub>DD</sub> ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	3.1875		39	μs
			1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V	17		39	μs
			1.6 V ≤ V <sub>DD</sub> ≤ 5.5 V	57		95	μs
Conversion time	t <sub>CONV</sub>	10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V ≤ V <sub>DD</sub> ≤ 5.5 V	2.375		39	μs
			2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	3.5625		39	μs
			2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V	17		39	μs
Zero-scale error <sup>Notes 1, 2</sup>	E <sub>ZS</sub>	10-bit resolution	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V			±0.60	%FSR
			1.6 V ≤ V <sub>DD</sub> ≤ 5.5 V <small>Note 3</small>			±0.85	%FSR
Full-scale error <sup>Notes 1, 2</sup>	E <sub>FS</sub>	10-bit resolution	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V			±0.60	%FSR
			1.6 V ≤ V <sub>DD</sub> ≤ 5.5 V <small>Note 3</small>			±0.85	%FSR
Integral linearity error <sup>Note 1</sup>	ILE	10-bit resolution	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V			±4.0	LSB
			1.6 V ≤ V <sub>DD</sub> ≤ 5.5 V <small>Note 3</small>			±6.5	LSB
Differential linearity error <sup>Note 1</sup>	DLE	10-bit resolution	1.8 V ≤ V <sub>DD</sub> ≤ 5.5 V			±2.0	LSB
			1.6 V ≤ V <sub>DD</sub> ≤ 5.5 V <small>Note 3</small>			±2.5	LSB
Analog input voltage	V <sub>AIN</sub>	ANI0 to ANI14		0		V <sub>DD</sub>	V
		ANI16 to ANI26		0		EV <sub>DD0</sub>	V
		Internal reference voltage (2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V, HS (high-speed main) mode)		V <sub>BGR</sub> <sup>Note 4</sup>			V
		Temperature sensor output voltage (2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V, HS (high-speed main) mode)		V <sub>TMPS25</sub> <sup>Note 4</sup>			V

**Notes** 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. When the conversion time is set to 57 μs (min.) and 95 μs (max.).

4. Refer to 2.6.2 Temperature sensor/internal reference voltage characteristics.

### 3. ELECTRICAL SPECIFICATIONS (G: INDUSTRIAL APPLICATIONS $T_A = -40$ to $+105^\circ\text{C}$ )

This chapter describes the following electrical specifications.

Target products G: Industrial applications  $T_A = -40$  to  $+105^\circ\text{C}$   
R5F100xxGxx

- Cautions 1.** The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.
- 2.** With products not provided with an  $\text{EV}_{\text{DD0}}$ ,  $\text{EV}_{\text{DD1}}$ ,  $\text{EV}_{\text{SS0}}$ , or  $\text{EV}_{\text{SS1}}$  pin, replace  $\text{EV}_{\text{DD0}}$  and  $\text{EV}_{\text{DD1}}$  with  $V_{\text{DD}}$ , or replace  $\text{EV}_{\text{SS0}}$  and  $\text{EV}_{\text{SS1}}$  with  $V_{\text{SS}}$ .
- 3.** The pins mounted depend on the product. Refer to 2.1 Port Function to 2.2.1 Functions for each product.
- 4.** Please contact Renesas Electronics sales office for derating of operation under  $T_A = +85^\circ\text{C}$  to  $+105^\circ\text{C}$ . Derating is the systematic reduction of load for the sake of improved reliability.

**Remark** When RL78/G13 is used in the range of  $T_A = -40$  to  $+85^\circ\text{C}$ , see **CHAPTER 2 ELECTRICAL SPECIFICATIONS ( $T_A = -40$  to  $+85^\circ\text{C}$ )**.

There are following differences between the products "G: Industrial applications ( $T_A = -40$  to  $+105^\circ\text{C}$ )" and the products "A: Consumer applications, and D: Industrial applications".

Parameter	Application	
	A: Consumer applications, D: Industrial applications	G: Industrial applications
Operating ambient temperature	$T_A = -40$ to $+85^\circ\text{C}$	$T_A = -40$ to $+105^\circ\text{C}$
Operating mode Operating voltage range	HS (high-speed main) mode: $2.7\text{ V} \leq V_{\text{DD}} \leq 5.5\text{ V}@1\text{ MHz}$ to $32\text{ MHz}$ $2.4\text{ V} \leq V_{\text{DD}} \leq 5.5\text{ V}@1\text{ MHz}$ to $16\text{ MHz}$ LS (low-speed main) mode: $1.8\text{ V} \leq V_{\text{DD}} \leq 5.5\text{ V}@1\text{ MHz}$ to $8\text{ MHz}$ LV (low-voltage main) mode: $1.6\text{ V} \leq V_{\text{DD}} \leq 5.5\text{ V}@1\text{ MHz}$ to $4\text{ MHz}$	HS (high-speed main) mode only: $2.7\text{ V} \leq V_{\text{DD}} \leq 5.5\text{ V}@1\text{ MHz}$ to $32\text{ MHz}$ $2.4\text{ V} \leq V_{\text{DD}} \leq 5.5\text{ V}@1\text{ MHz}$ to $16\text{ MHz}$
High-speed on-chip oscillator clock accuracy	$1.8\text{ V} \leq V_{\text{DD}} \leq 5.5\text{ V}$ $\pm 1.0\%@ T_A = -20$ to $+85^\circ\text{C}$ $\pm 1.5\%@ T_A = -40$ to $-20^\circ\text{C}$ $1.6\text{ V} \leq V_{\text{DD}} < 1.8\text{ V}$ $\pm 5.0\%@ T_A = -20$ to $+85^\circ\text{C}$ $\pm 5.5\%@ T_A = -40$ to $-20^\circ\text{C}$	$2.4\text{ V} \leq V_{\text{DD}} \leq 5.5\text{ V}$ $\pm 2.0\%@ T_A = +85$ to $+105^\circ\text{C}$ $\pm 1.0\%@ T_A = -20$ to $+85^\circ\text{C}$ $\pm 1.5\%@ T_A = -40$ to $-20^\circ\text{C}$
Serial array unit	UART CSI: $f_{\text{CLK}}/2$ (supporting 16 Mbps), $f_{\text{CLK}}/4$ Simplified I <sup>2</sup> C communication	UART CSI: $f_{\text{CLK}}/4$ Simplified I <sup>2</sup> C communication
IICA	Normal mode Fast mode Fast mode plus	Normal mode Fast mode
Voltage detector	Rise detection voltage: 1.67 V to 4.06 V (14 levels) Fall detection voltage: 1.63 V to 3.98 V (14 levels)	Rise detection voltage: 2.61 V to 4.06 V (8 levels) Fall detection voltage: 2.55 V to 3.98 V (8 levels)

(Remark is listed on the next page.)

**( $T_A = -40$  to  $+105^\circ\text{C}$ ,  $2.4\text{ V} \leq \text{EV}_{\text{DD}0} = \text{EV}_{\text{DD}1} \leq \text{V}_{\text{DD}} \leq 5.5\text{ V}$ ,  $\text{V}_{\text{SS}} = \text{EV}_{\text{SS}0} = \text{EV}_{\text{SS}1} = 0\text{ V}$ ) (2/5)**

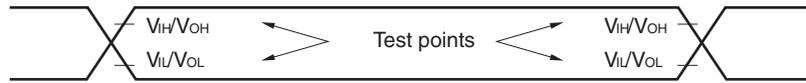
Items	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output current, $I_{\text{OL}}^{\text{Note 1}}$	I <sub>OL1</sub>	Per pin for P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147			8.5 <sup>Note 2</sup>	mA
		Per pin for P60 to P63			15.0 <sup>Note 2</sup>	mA
		Total of P00 to P04, P07, P32 to P37, P40 to P47, P102 to P106, P120, P125 to P127, P130, P140 to P145 (When duty $\leq 70\%$ <sup>Note 3</sup> )	$4.0\text{ V} \leq \text{EV}_{\text{DD}0} \leq 5.5\text{ V}$		40.0	mA
			$2.7\text{ V} \leq \text{EV}_{\text{DD}0} < 4.0\text{ V}$		15.0	mA
			$2.4\text{ V} \leq \text{EV}_{\text{DD}0} < 2.7\text{ V}$		9.0	mA
		Total of P05, P06, P10 to P17, P30, P31, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100, P101, P110 to P117, P146, P147 (When duty $\leq 70\%$ <sup>Note 3</sup> )	$4.0\text{ V} \leq \text{EV}_{\text{DD}0} \leq 5.5\text{ V}$		40.0	mA
			$2.7\text{ V} \leq \text{EV}_{\text{DD}0} < 4.0\text{ V}$		35.0	mA
	$2.4\text{ V} \leq \text{EV}_{\text{DD}0} < 2.7\text{ V}$			20.0	mA	
	Total of all pins (When duty $\leq 70\%$ <sup>Note 3</sup> )			80.0	mA	
	I <sub>OL2</sub>	Per pin for P20 to P27, P150 to P156				0.4 <sup>Note 2</sup>
Total of all pins (When duty $\leq 70\%$ <sup>Note 3</sup> )		$2.4\text{ V} \leq \text{V}_{\text{DD}} \leq 5.5\text{ V}$			5.0	mA

- Notes**
- Value of current at which the device operation is guaranteed even if the current flows from an output pin to the EV<sub>SS0</sub>, EV<sub>SS1</sub> and V<sub>SS</sub> pin.
  - Do not exceed the total current value.
  - Specification under conditions where the duty factor  $\leq 70\%$ .  
The output current value that has changed to the duty factor  $> 70\%$  the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).
    - Total output current of pins =  $(I_{\text{OL}} \times 0.7)/(n \times 0.01)$   
<Example> Where  $n = 80\%$  and  $I_{\text{OL}} = 10.0\text{ mA}$   
Total output current of pins =  $(10.0 \times 0.7)/(80 \times 0.01) \cong 8.7\text{ mA}$
 However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

**Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

### 3.5 Peripheral Functions Characteristics

#### AC Timing Test Points



#### 3.5.1 Serial array unit

##### (1) During communication at same potential (UART mode)

( $T_A = -40$  to  $+105^\circ\text{C}$ ,  $2.4\text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5\text{ V}$ ,  $V_{SS} = EV_{SS0} = EV_{SS1} = 0\text{ V}$ )

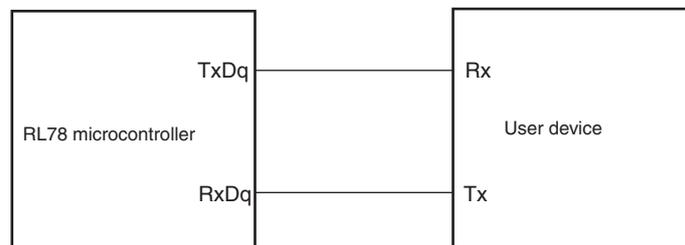
Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
Transfer rate <sup>Note 1</sup>		Theoretical value of the maximum transfer rate $f_{CLK} = 32\text{ MHz}$ , $f_{MCK} = f_{CLK}$		$f_{MCK}/12$ <sup>Note 2</sup>	bps
				2.6	Mbps

**Notes 1.** Transfer rate in the SNOOZE mode is 4800 bps only.

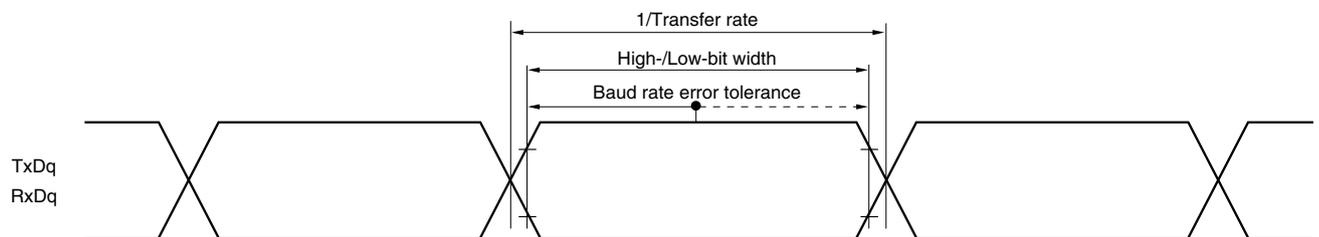
**2.** The following conditions are required for low voltage interface when  $EV_{DD0} < V_{DD}$ .  
 $2.4\text{ V} \leq EV_{DD0} < 2.7\text{ V}$  : MAX. 1.3 Mbps

**Caution** Select the normal input buffer for the RxDq pin and the normal output mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg).

#### UART mode connection diagram (during communication at same potential)



#### UART mode bit width (during communication at same potential) (reference)

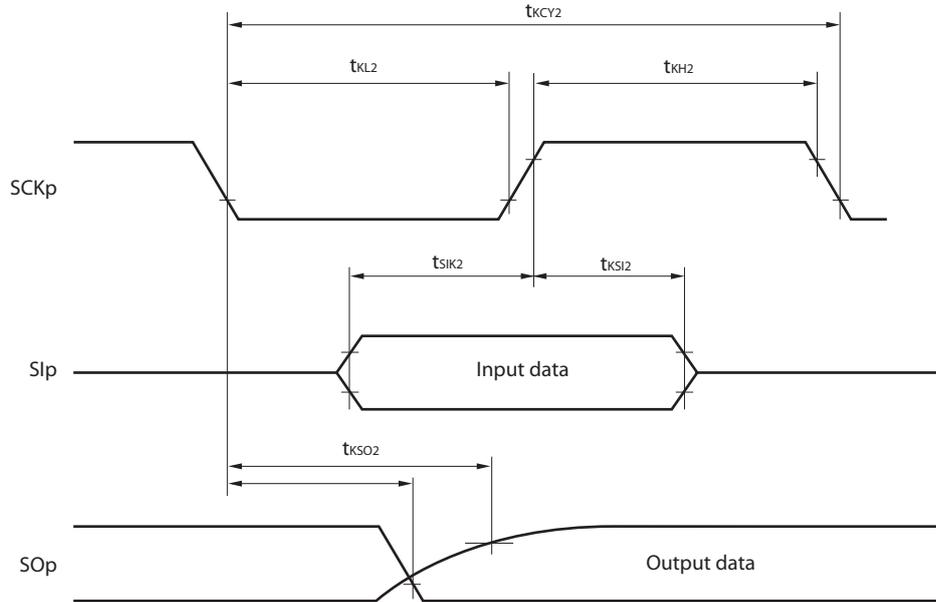


**Remarks 1.** q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)

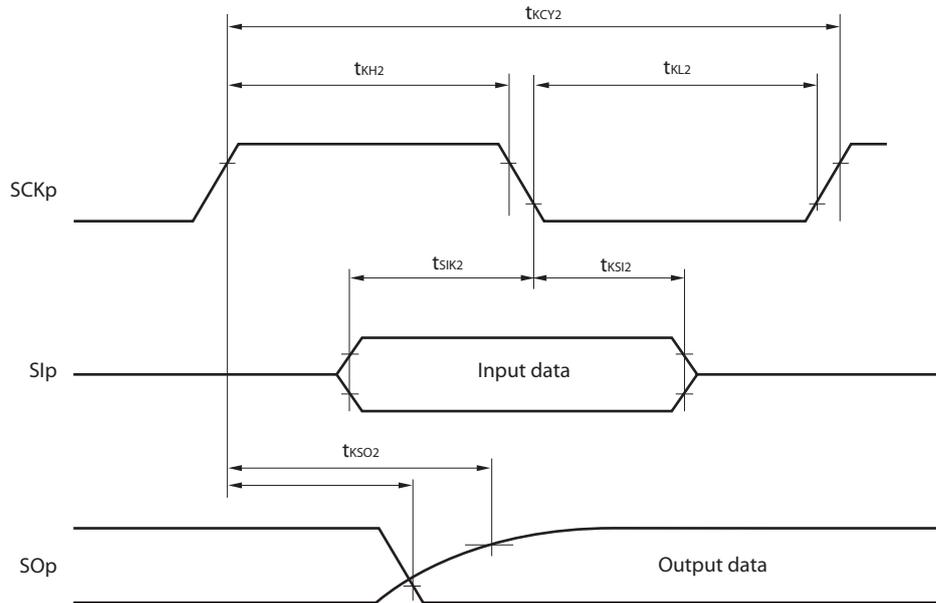
**2.**  $f_{MCK}$ : Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

**CSI mode serial transfer timing (slave mode) (during communication at different potential)  
(When  $\text{DAPmn} = 0$  and  $\text{CKPmn} = 0$ , or  $\text{DAPmn} = 1$  and  $\text{CKPmn} = 1$ .)**



**CSI mode serial transfer timing (slave mode) (during communication at different potential)  
(When  $\text{DAPmn} = 0$  and  $\text{CKPmn} = 1$ , or  $\text{DAPmn} = 1$  and  $\text{CKPmn} = 0$ .)**



- Remarks 1.** p: CSI number (p = 00, 01, 10, 20, 30, 31), m: Unit number,  
n: Channel number (mn = 00, 01, 02, 10, 12, 13), g: PIM and POM number (g = 0, 1, 4, 5, 8, 14)
- 2.** CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential.  
Use other CSI for communication at different potential.

### 3.6 Analog Characteristics

#### 3.6.1 A/D converter characteristics

##### Classification of A/D converter characteristics

Input channel	Reference Voltage		
	Reference voltage (+) = $AV_{REFP}$ Reference voltage (-) = $AV_{REFM}$	Reference voltage (+) = $V_{DD}$ Reference voltage (-) = $V_{SS}$	Reference voltage (+) = $V_{BGR}$ Reference voltage (-) = $AV_{REFM}$
ANI0 to ANI14	Refer to <b>3.6.1 (1)</b> .	Refer to <b>3.6.1 (3)</b> .	Refer to <b>3.6.1 (4)</b> .
ANI16 to ANI26	Refer to <b>3.6.1 (2)</b> .		
Internal reference voltage Temperature sensor output voltage	Refer to <b>3.6.1 (1)</b> .		–

(1) When reference voltage (+) =  $AV_{REFP}/ANI0$  ( $ADREFP1 = 0$ ,  $ADREFP0 = 1$ ), reference voltage (-) =  $AV_{REFM}/ANI1$  ( $ADREFM = 1$ ), target pin : ANI2 to ANI14, internal reference voltage, and temperature sensor output voltage

( $T_A = -40$  to  $+105^\circ\text{C}$ ,  $2.4\text{ V} \leq AV_{REFP} \leq V_{DD} \leq 5.5\text{ V}$ ,  $V_{SS} = 0\text{ V}$ , Reference voltage (+) =  $AV_{REFP}$ , Reference voltage (-) =  $AV_{REFM} = 0\text{ V}$ )

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error <sup>Note 1</sup>	AINL	10-bit resolution $AV_{REFP} = V_{DD}$ <sup>Note 3</sup>	$2.4\text{ V} \leq AV_{REFP} \leq 5.5\text{ V}$		1.2	$\pm 3.5$	LSB
Conversion time	$t_{CONV}$	10-bit resolution Target pin: ANI2 to ANI14	$3.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	2.125		39	$\mu\text{s}$
			$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	3.1875		39	$\mu\text{s}$
			$2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	17		39	$\mu\text{s}$
		10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	$3.6\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	2.375		39	$\mu\text{s}$
			$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	3.5625		39	$\mu\text{s}$
			$2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	17		39	$\mu\text{s}$
Zero-scale error <sup>Notes 1, 2</sup>	$E_{ZS}$	10-bit resolution $AV_{REFP} = V_{DD}$ <sup>Note 3</sup>	$2.4\text{ V} \leq AV_{REFP} \leq 5.5\text{ V}$			$\pm 0.25$	%FSR
Full-scale error <sup>Notes 1, 2</sup>	$E_{FS}$	10-bit resolution $AV_{REFP} = V_{DD}$ <sup>Note 3</sup>	$2.4\text{ V} \leq AV_{REFP} \leq 5.5\text{ V}$			$\pm 0.25$	%FSR
Integral linearity error <sup>Note 1</sup>	ILE	10-bit resolution $AV_{REFP} = V_{DD}$ <sup>Note 3</sup>	$2.4\text{ V} \leq AV_{REFP} \leq 5.5\text{ V}$			$\pm 2.5$	LSB
Differential linearity error <sup>Note 1</sup>	DLE	10-bit resolution $AV_{REFP} = V_{DD}$ <sup>Note 3</sup>	$2.4\text{ V} \leq AV_{REFP} \leq 5.5\text{ V}$			$\pm 1.5$	LSB
Analog input voltage	$V_{AIN}$	ANI2 to ANI14		0		$AV_{REFP}$	V
		Internal reference voltage output ( $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ , HS (high-speed main) mode)				$V_{BGR}$ <sup>Note 4</sup>	V
		Temperature sensor output voltage ( $2.4\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ , HS (high-speed main) mode)				$V_{TMPS25}$ <sup>Note 4</sup>	V

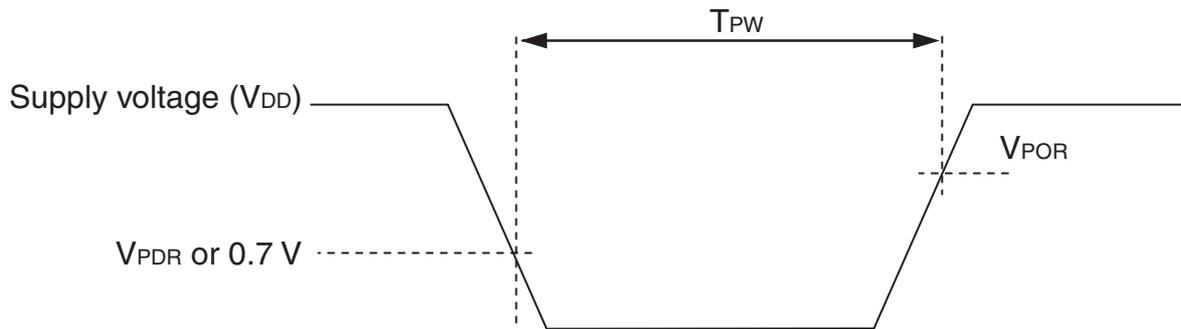
(Notes are listed on the next page.)

3.6.3 POR circuit characteristics

( $T_A = -40$  to  $+105^\circ\text{C}$ ,  $V_{SS} = 0$  V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	$V_{POR}$	Power supply rise time	1.45	1.51	1.57	V
	$V_{PDR}$	Power supply fall time	1.44	1.50	1.56	V
Minimum pulse width	$T_{PW}$		300			$\mu\text{s}$

**Note** Minimum time required for a POR reset when  $V_{DD}$  exceeds below  $V_{PDR}$ . This is also the minimum time required for a POR reset from when  $V_{DD}$  exceeds below 0.7 V to when  $V_{DD}$  exceeds  $V_{POR}$  while STOP mode is entered or the main system clock is stopped through setting bit 0 (HIOSTOP) and bit 7 (MSTOP) in the clock operation status control register (CSC).



### 3.6.5 Power supply voltage rising slope characteristics

( $T_A = -40$  to  $+105^\circ\text{C}$ ,  $V_{SS} = 0$  V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	$S_{VDD}$				54	V/ms

**Caution** Make sure to keep the internal reset state by the LVD circuit or an external reset until  $V_{DD}$  reaches the operating voltage range shown in 3.4 AC Characteristics.

### 3.7 RAM Data Retention Characteristics

( $T_A = -40$  to  $+105^\circ\text{C}$ ,  $V_{SS} = 0$  V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention supply voltage	$V_{DDDR}$		1.44 <sup>Note</sup>		5.5	V

**Note** This depends on the POR detection voltage. For a falling voltage, data in RAM are retained until the voltage reaches the level that triggers a POR reset but not once it reaches the level at which a POR reset is generated.

